

WHAT IS CLAIMED IS:

1. A 1-Gigabyte capacity memory module comprising 36 integrated circuits of type 256-Megabit SDRAM organized as 64 Meg by 4 bits in a TSOP package having an approximate dimension of 5.25 inches wide by 2.05 inches high, the integrated circuits arranged in two rows on each of two surfaces of a printed circuit board.
2. The memory module of Claim 1, wherein the integrated circuits are Double Data Rate SDRAM.
3. A 2-Gigabyte capacity memory module comprising 36 integrated circuits of type 512-Megabit SDRAM organized as 128 Meg by 4 bits in a TSOP package having an approximate dimension of 5.25 inches wide by 2.05 inches high, the integrated circuits arranged in two rows on each of two surfaces of a printed circuit board.
4. The memory module of Claim 3, wherein the integrated circuits are Double Data Rate SDRAM.